ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1	IDC Web Site for Information on IDC 1752 Standard					Form Type * Declaration Class *			rials and Mfg Information								
Supplier Information																	
Company	Company name*				Company unique ID			Unique ID Authority					Response	Response Date*			
onsemi														2024-05-03			
Contact Name				Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*					
Product-I	Env-Stewar	ls		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Authorize	Authorized Representative*				Title - Representative			Phone - Representative*				Email - Representative*					
Product-I	Env-Stewar	ls		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester	quester Item Number Mfr Item		Number	Number Mfr Item Name			Effective Da	ate Ve	ersion	Mai	Manufacturing Site		eight*	UOM	Unit Type	
	MT9J003I DP			3I12STCV2-	12STCV2- 10 MP 1/2.3 CIS			2024-05-03			TW	TWU		40.0	mg	Each	
Manufacturing Process Information																	
	Terminal Plating / Grid Array Material		erminal Base Alloy J-STD-0		J-STD-020 MS	L Rating	g Peak Proce		ess Body Temperature Max Time at Pea		Max Time at Peak	Temperature Number		of Reflow Cyc	les		
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 4			260		C		30	second	s 3					
Comments																	
For more	information	regarding material com	position	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	52.87	mg		Misc.	proprietary data		0.2009	mg
			Supplier	Silicon (Si)	7440-21-3		52.1457	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5234	mg
Die Attach	2.57	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9638	mg
			Supplier	Ethylene Glycol	107-21-1		0.0257	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0771	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.5397	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9637	mg
Imaging Lens	57.43	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.8715	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.8715	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.8715	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.8715	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2871	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.8715	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.8715	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		39.9138	mg
Lid Attach	2.4	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		1.08	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.48	mg
			Supplier	Filler (SiO2)	68909-20-6		0.3	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.012	mg
			Supplier	Curative	Proprietary Data		0.048	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.48	mg
Mold Compound-Black	45.77	mg		Phenolic Resin	proprietary data		6.8655	mg
			Supplier	Oxirane	39817-09-9		6.8655	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.3731	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4577	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.2928	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.9154	mg
Substrate and Solder Mask	78.72	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		16.6808	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.0312	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2598	mg

			Supplier	Acetophenone Derivative	Proprietary Data	1.5429	mg
			Supplier	Carbon Black (C)	1333-86-4	0.2519	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2598	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.0858	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	10.2966	mg
			Supplier	Copper (Cu)	7440-50-8	37.329	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	7.9822	mg
Wire Bond - Au	0.24	mg	Supplier	Gold (Au)	7440-57-5	0.24	mg